

INFORMATION ONLY NOTIFICATION

This is to inform you that a change is being made to the following product(s). This notification is for your information only.

If you have any questions concerning this change, please contact:

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Implementation of change:

Expected 1st Device Shipment Date: 2009/07/08

Earliest Year/Work Week of Changed Product: 0928

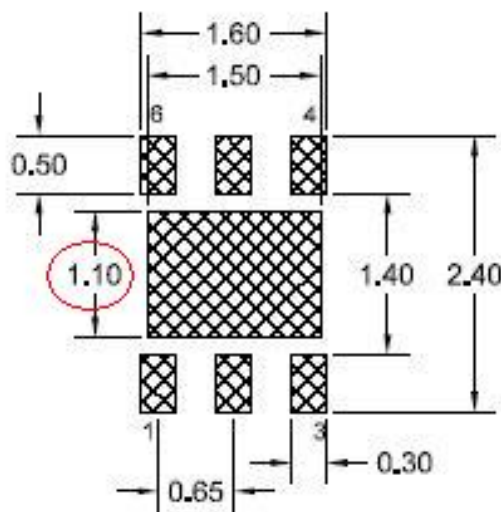
Change Type Description: Package Change (Lead Frame)

Description of Change (From): The current exposed dap width dimension is 1.10mm.

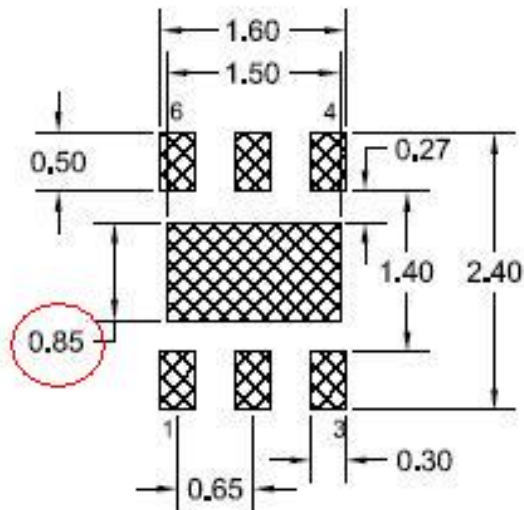
Description of Change (To): The new exposed dap width dimension will be changed to 0.85mm.

Reason for Change : The reduction in width of the exposed dap-pad will increase the lead-to-dap clearance for minimum of 0.25mm.

Change From



Change To



Product Id Description : Selected Fairchild Semiconductor's devices assembled in MLP 2x2 6 lead package will be affected by this change. Note the recommended land pattern will be updated to reflect this change; however, either the existing or the new recommended land pattern can be used. Please refer to the Affected FSIDs section.

Affected FSIDs :

FPF1015	FPF1016	FPF1017
FPF1018		